



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

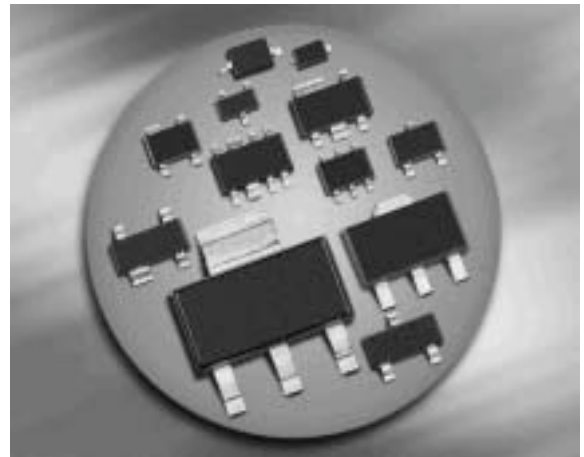
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

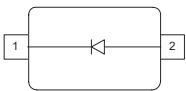


**Silicon Schottky Diode**

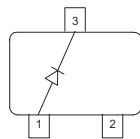
- General-purpose diode for high-speed switching
- Circuit protection
- Voltage clamping
- High-level detecting and mixing
- BAS70-04S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



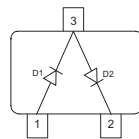
**BAS170W**  
**BAS70-02L**  
**BAS70-02W**



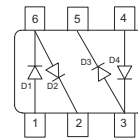
**BAS70**



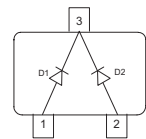
**BAS70-04**  
**BAS70-04W**



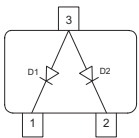
**BAS70-04S**



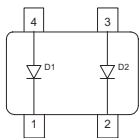
**BAS70-05**  
**BAS70-05W**



**BAS70-06**  
**BAS70-06W**



**BAS70-07**  
**BAS70-07W**



<sup>1</sup>Pb-containing package may be available upon special request

Type	Package	Configuration	$L_S$ (nH)	Marking
BAS170W	SOD323	single	1.8	white 7
BAS70	SOT23	single	1.8	73s
BAS70-02L	TSLP-2-1	single, leadless	0.4	F
BAS70-02W	SCD80	single	0.6	73
BAS70-04	SOT23	series	1.8	74s
BAS70-04S	SOT363	dual series	1.6	74s
BAS70-04W	SOT323	series	1.4	74s
BAS70-05	SOT23	common cathode	1.8	75s
BAS70-05W	SOT323	common cathode	1.4	75s
BAS70-06	SOT23	common anode	1.8	76s
BAS70-06W	SOT323	common anode	1.4	76s
BAS70-07	SOT143	parallel pair	2	77s
BAS70-07W	SOT343	parallel pair	1.8	77s

**Maximum Ratings at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	70	V
Forward current	$I_F$	70	mA
Non-repetitive peak surge forward current $t \leq 10\text{ms}$	$I_{FSM}$	100	
Total power dissipation	$P_{tot}$		mW
BAS70, BAS70-07, $T_S \leq 72^\circ\text{C}$		250	
BAS70-02L, $T_S \leq 117^\circ\text{C}$		250	
BAS70-02W, $T_S \leq 107^\circ\text{C}$		250	
BAS70-04, BAS70-06, $T_S \leq 48^\circ\text{C}$		250	
BAS70-04S/W/-06W, BAS170W, $T_S \leq 97^\circ\text{C}$		250	
BAS70-05, $T_S \leq 22^\circ\text{C}$		250	
BAS70-05W, $T_S \leq 90^\circ\text{C}$		250	
BAS70-07W, $T_S \leq 114^\circ\text{C}$		250	
Junction temperature	$T_j$	150	$^\circ\text{C}$
Operating temperature range	$T_{op}$	-55 ... 125	
Storage temperature	$T_{stg}$	-55 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$		K/W
BAS70, BAS70-07		≤ 310	
BAS70-02L, BAS70-02W		≤ 130	
BAS70-04, BAS70-06		≤ 170	
BAS70-04S/W, BAS70-06W		≤ 410	
BAS70-05		≤ 210	
BAS70-05W		≤ 510	
BAS70-07W		≤ 240	
BAS170W		≤ 145	

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Breakdown voltage $I_{(BR)} = 10 \mu\text{A}$	$V_{(BR)}$	70	-	-	V
Reverse current $V_R = 50 \text{ V}$	$I_R$	-	-	0.1	$\mu\text{A}$
Forward voltage $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 15 \text{ mA}$	$V_F$	300 600 720	375 705 880	410 750 1000	mV
Forward voltage matching <sup>2)</sup> $I_F = 10 \text{ mA}$	$\Delta V_F$	-	-	20	

<sup>1</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

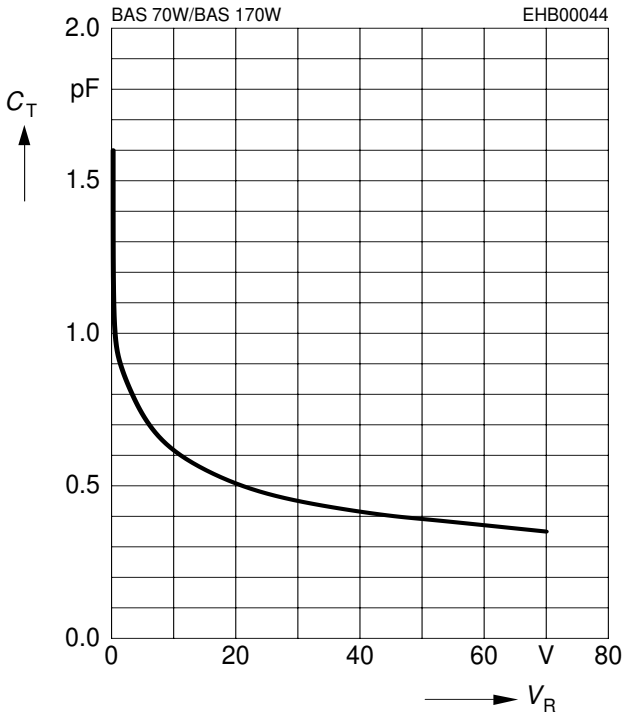
<sup>2</sup> $\Delta V_F$  is the difference between lowest and highest  $V_F$  in a multiple diode component.

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics</b>					
Diode capacitance $V_R = 0$ , $f = 1$ MHz	$C_T$	-	1.5	2	pF
Forward resistance $I_F = 10$ mA, $f = 10$ kHz	$r_f$	-	34	-	$\Omega$
Charge carrier life time $I_F = 25$ mA	$\tau_{rr}$	-	-	100	ps

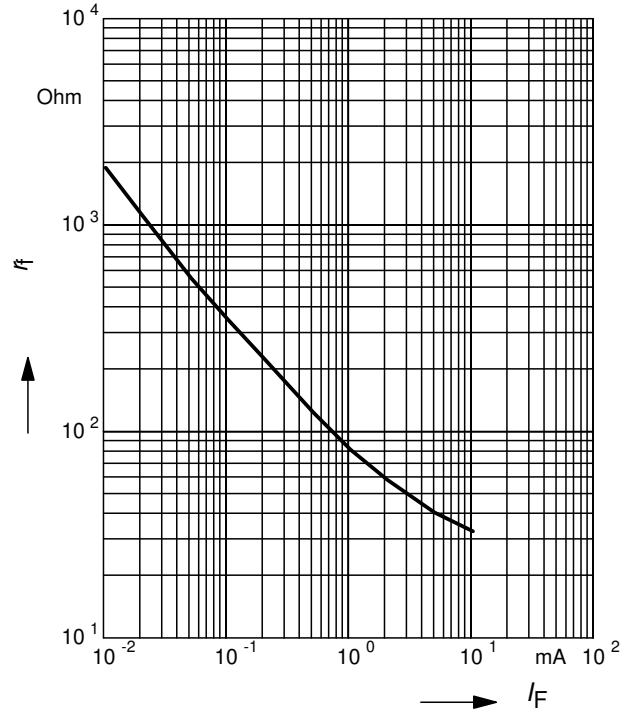
**Diode capacitance  $C_T = f(V_R)$**

$f = 1\text{MHz}$



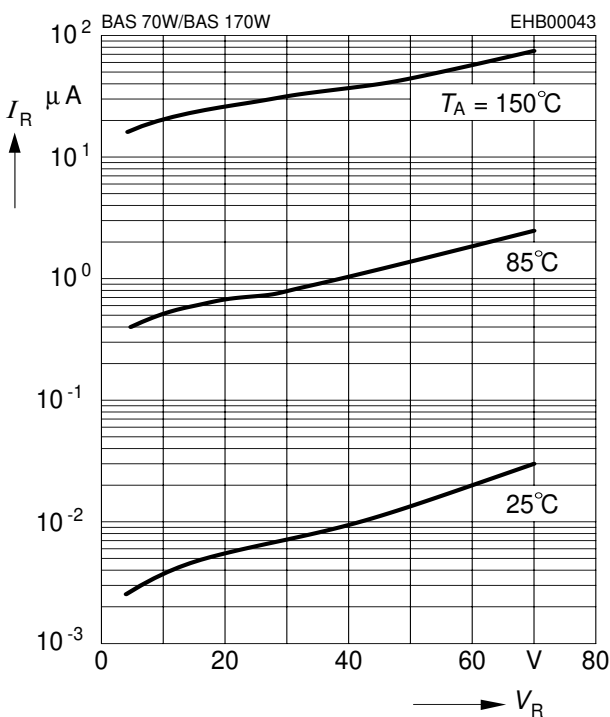
**Forward resistance  $r_f = f(I_F)$**

$f = 10\text{kHz}$



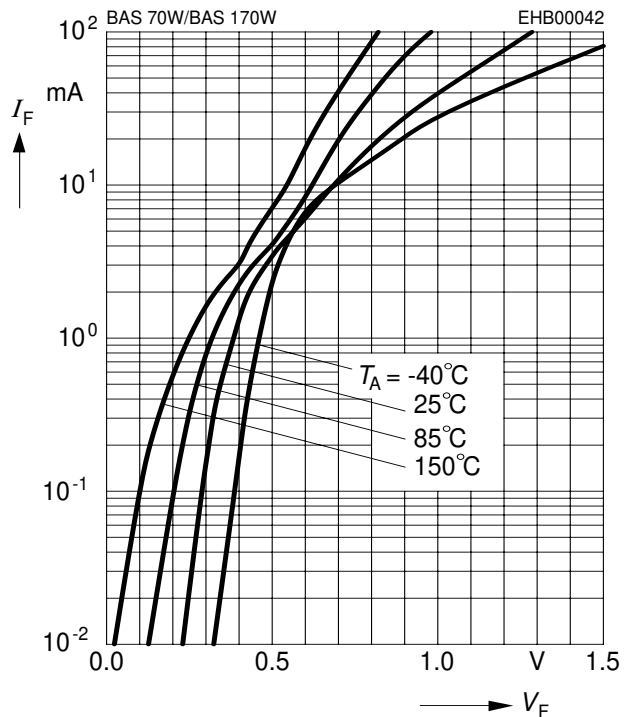
**Reverse current  $I_R = f(V_R)$**

$T_A = \text{Parameter}$



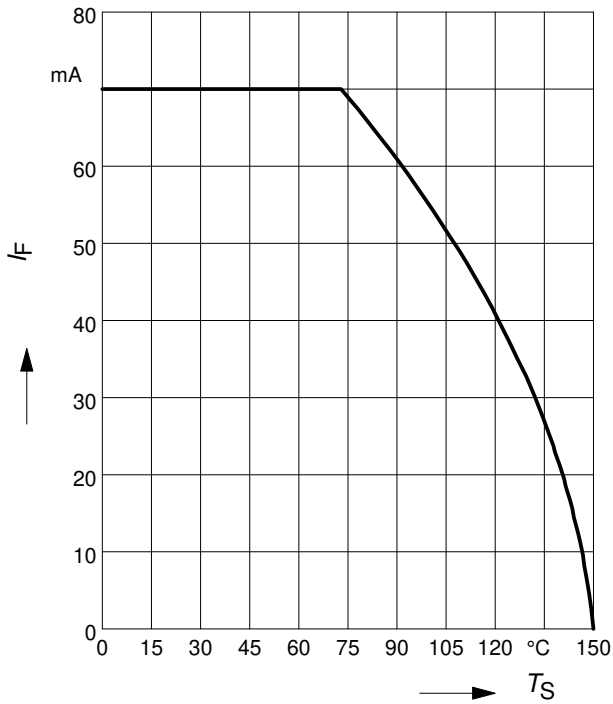
**Forward current  $I_F = f(V_F)$**

$T_A = \text{Parameter}$



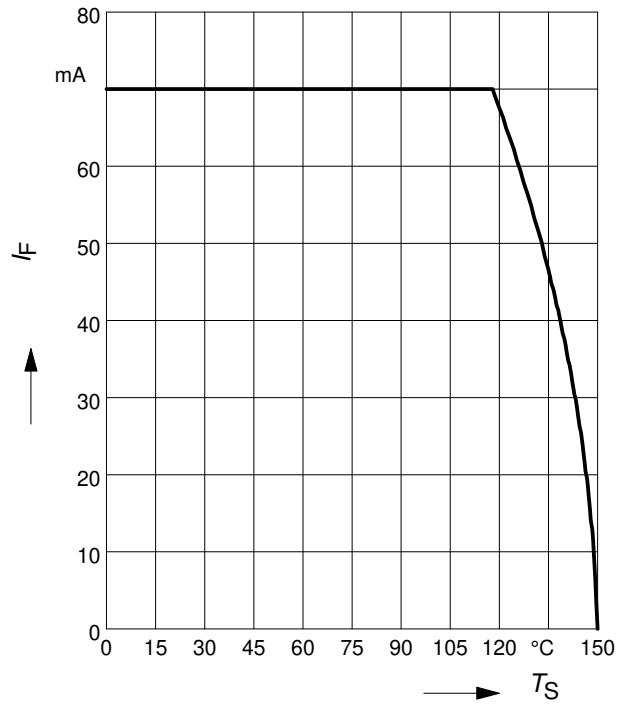
**Forward current  $I_F = f(T_S)$**

BAS70, BAS70-07



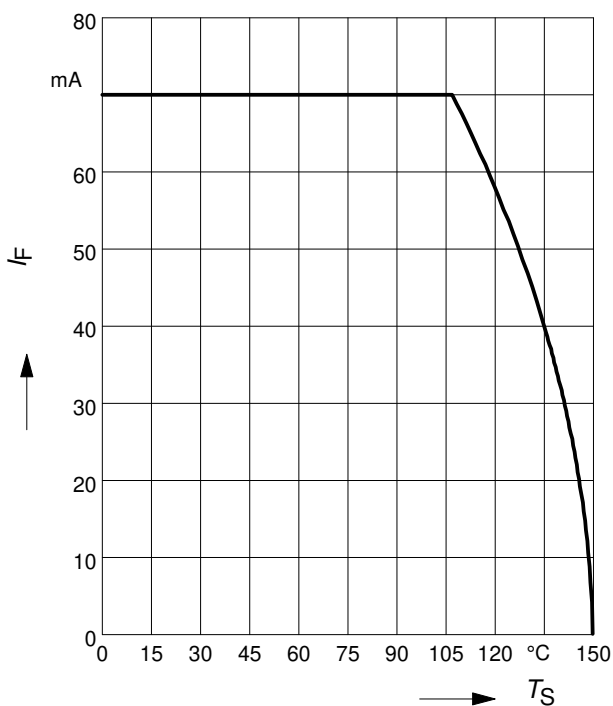
**Forward current  $I_F = f(T_S)$**

BAS70-02L



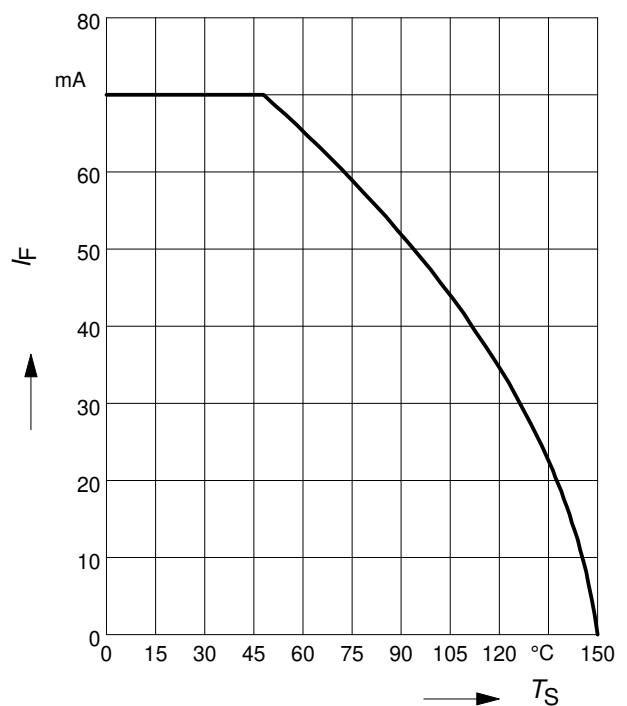
**Forward current  $I_F = f(T_S)$**

BAS70-02W

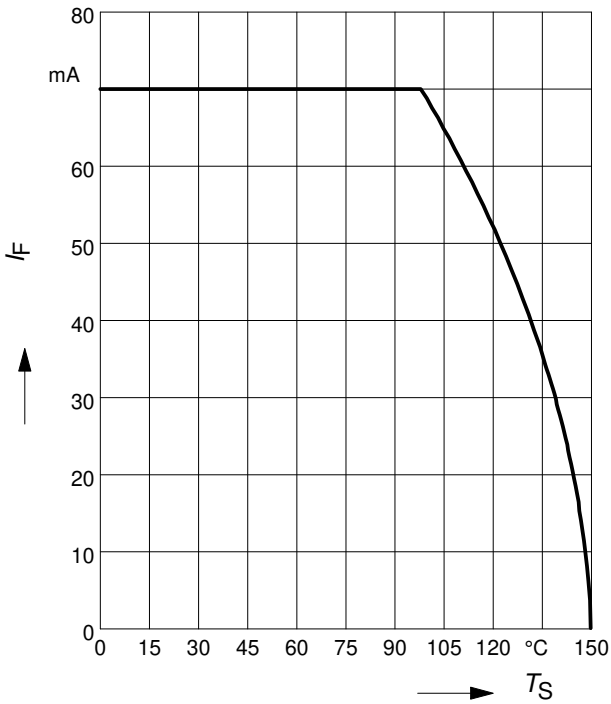


**Forward current  $I_F = f(T_S)$**

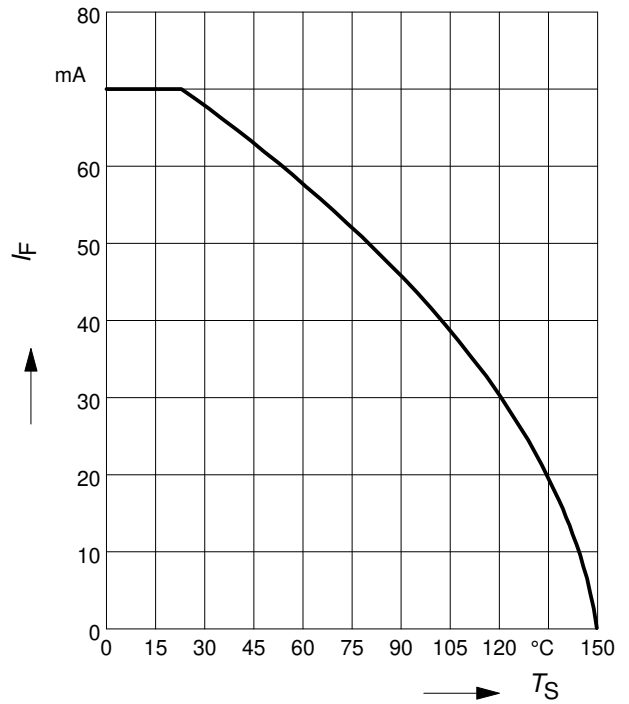
BAS70-04, BAS70-06



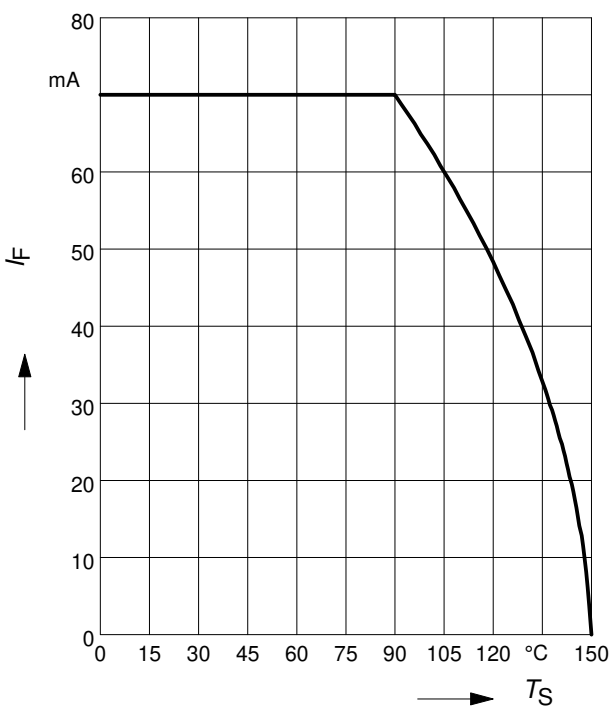
**Forward current  $I_F = f(T_S)$**   
 BAS70-04S/W, BAS70-06W, BAS170W



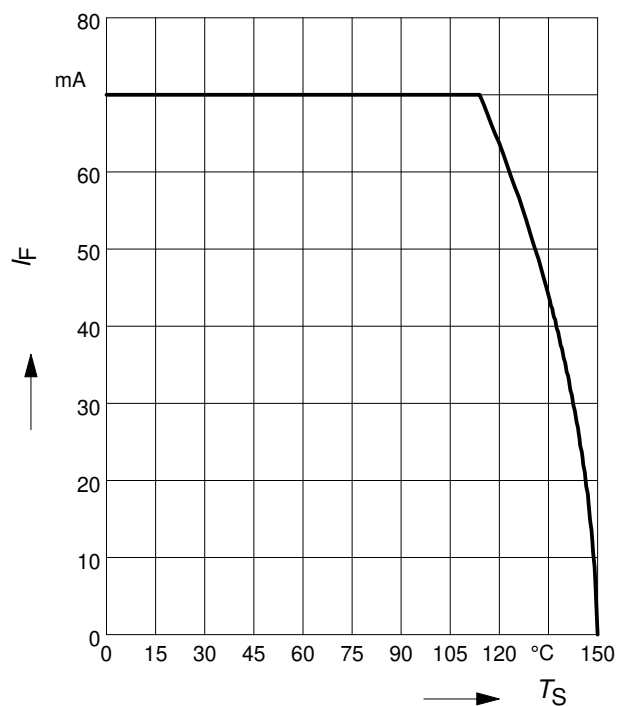
**Forward current  $I_F = f(T_S)$**   
 BAS70-05



**Forward current  $I_F = f(T_S)$**   
 BAS70-05W



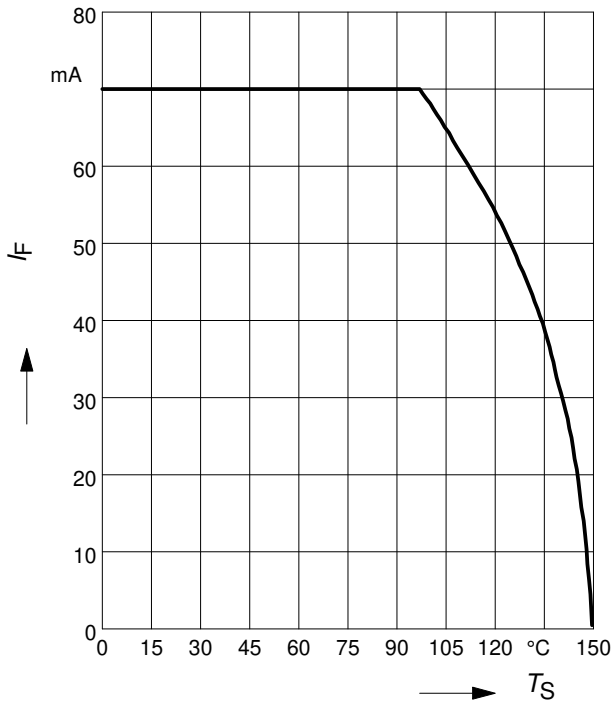
**Forward current  $I_F = f(T_S)$**   
 BAS70-07W





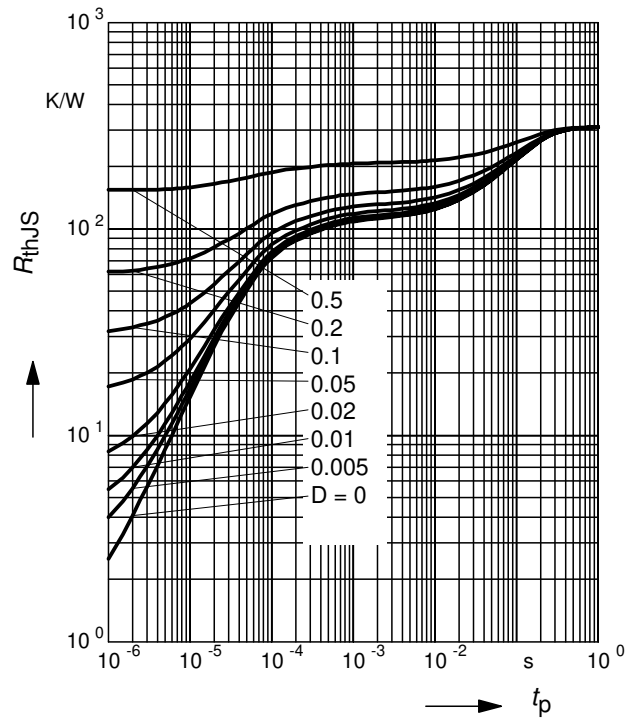
**Forward current  $I_F = f(T_S)$**

BAS170W



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

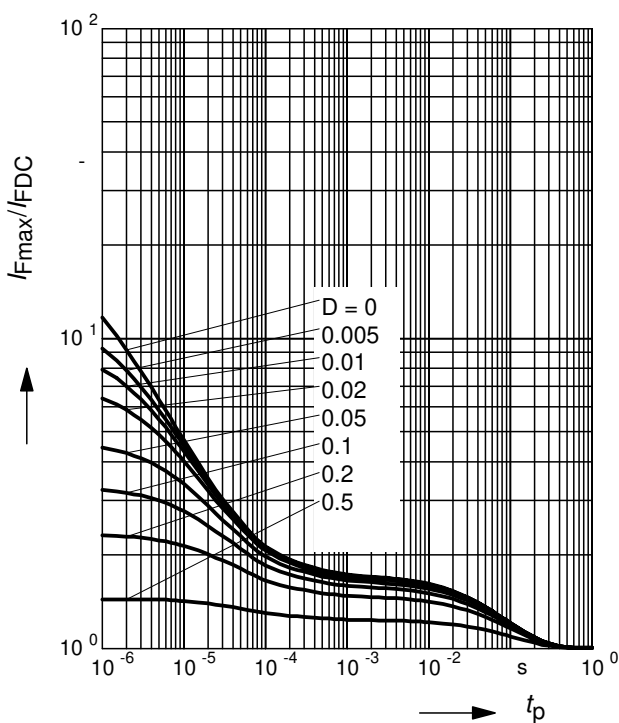
BAS70



**Permissible Pulse Load**

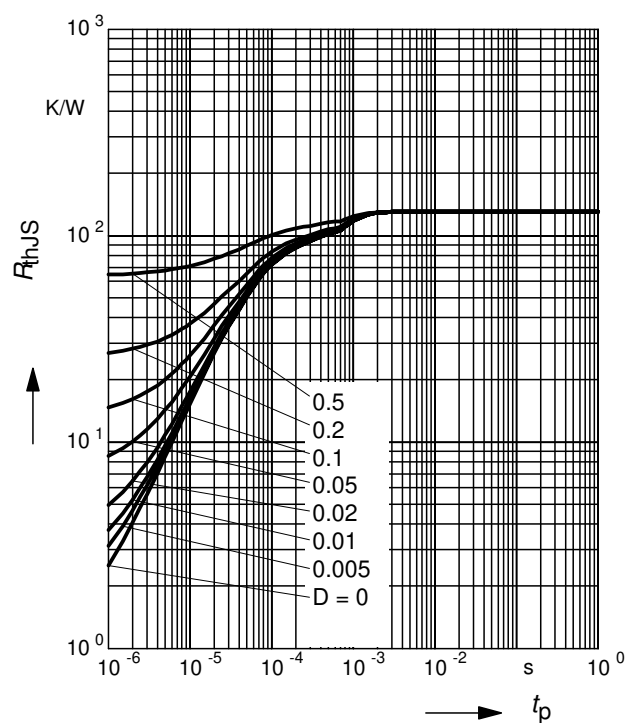
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS70



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

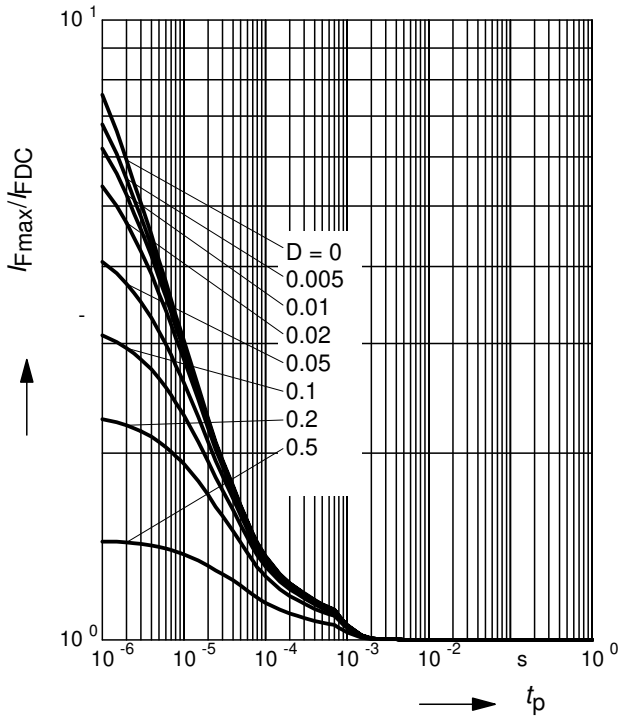
BAS70-02L



**Permissible Pulse Load**

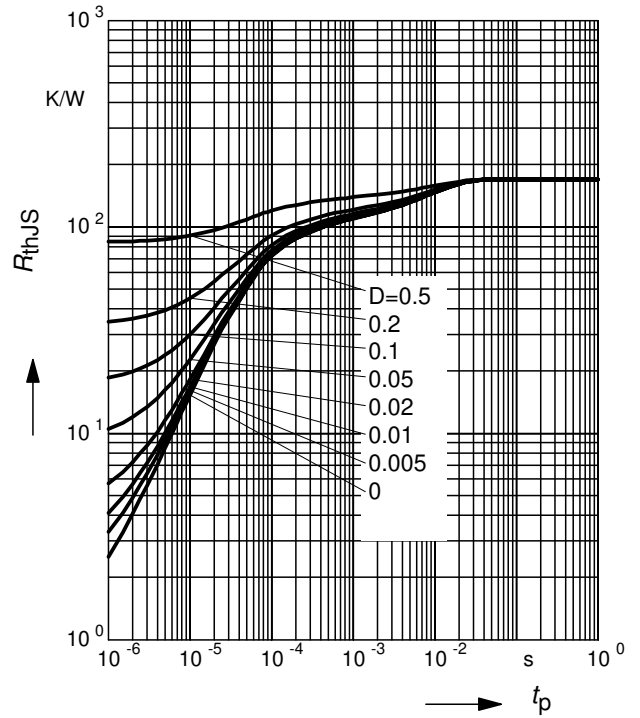
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS70-02L



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

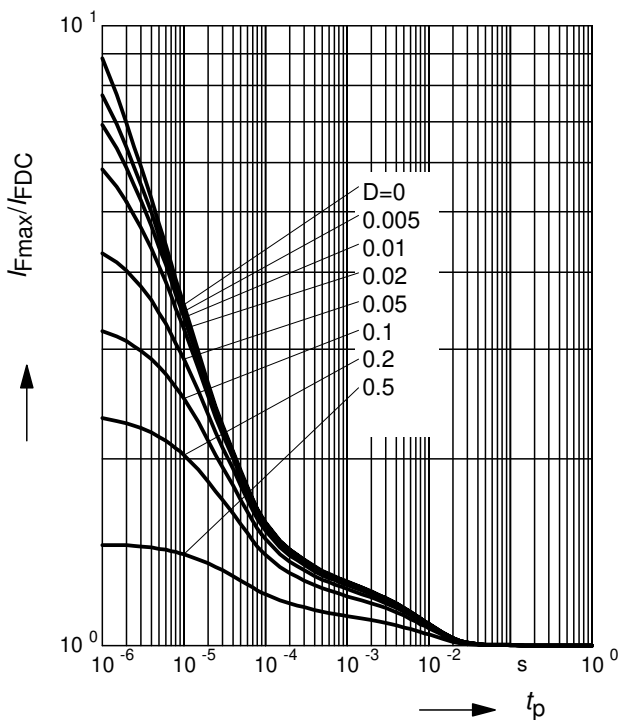
BAS70-02W



**Permissible Pulse Load**

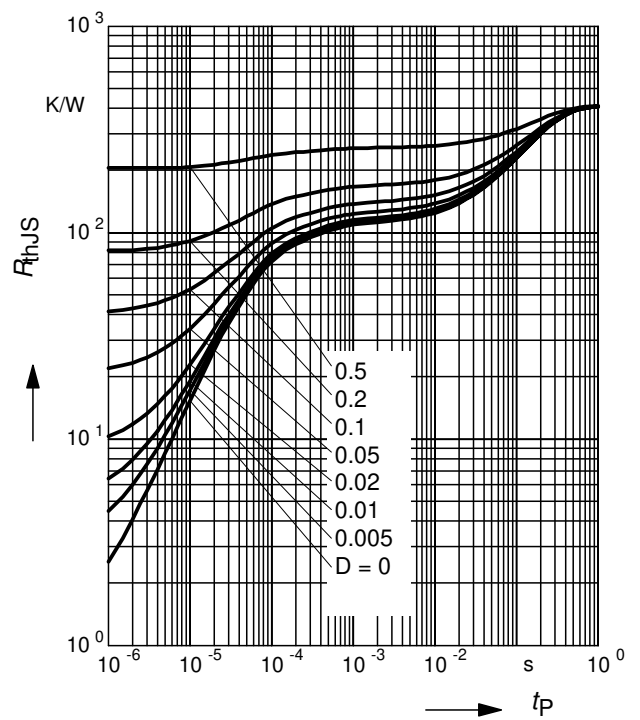
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS70-02W



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

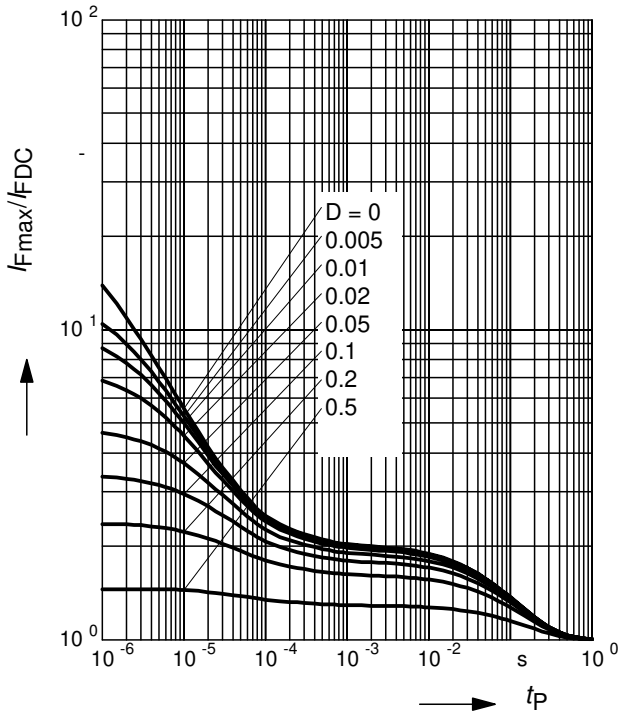
BAS70-04, BAS70-06



**Permissible Pulse Load**

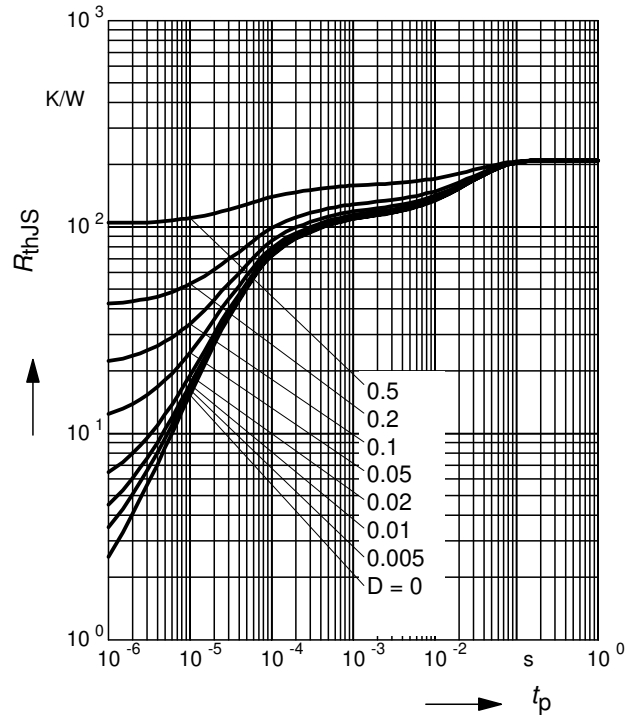
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAS70-04, BAS70-06



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

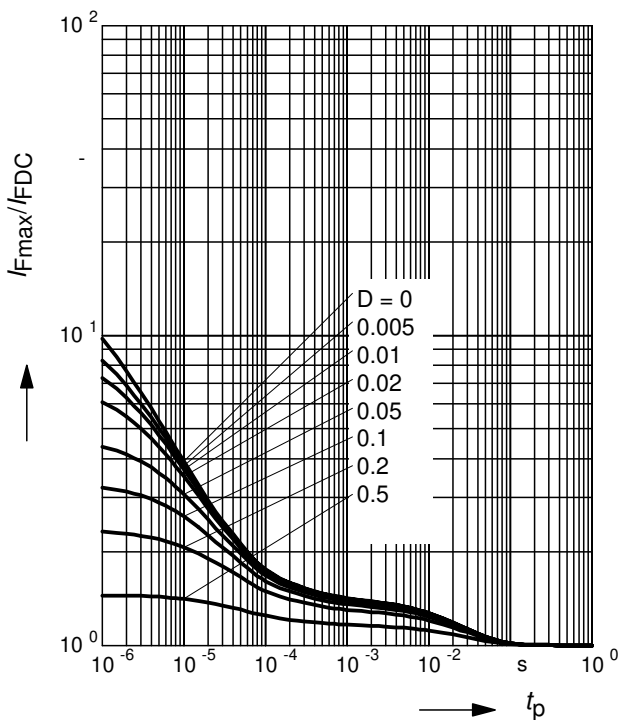
BAS70-04S



**Permissible Pulse Load**

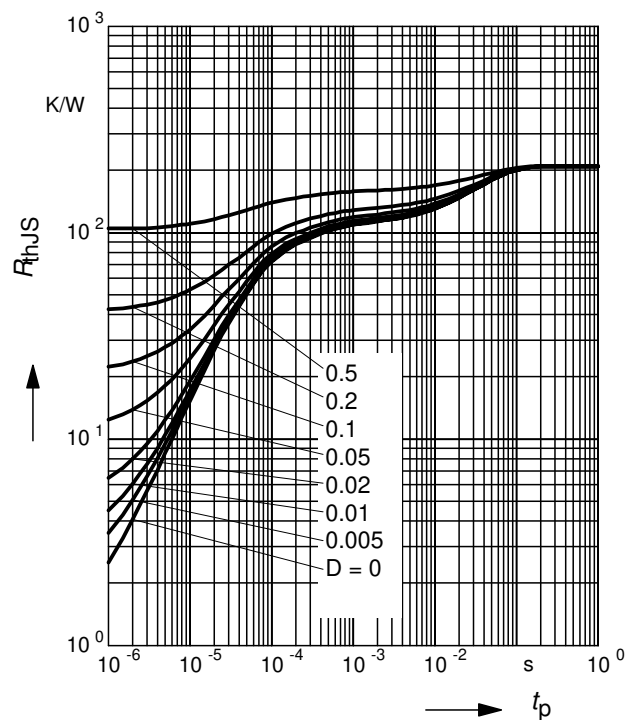
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAS70-04S



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

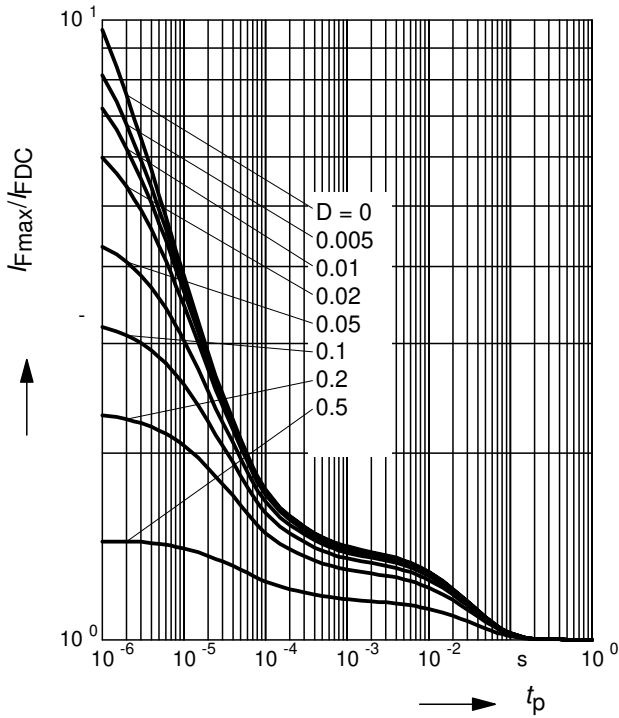
BAS70-04W, BAS70-06W



**Permissible Pulse Load**

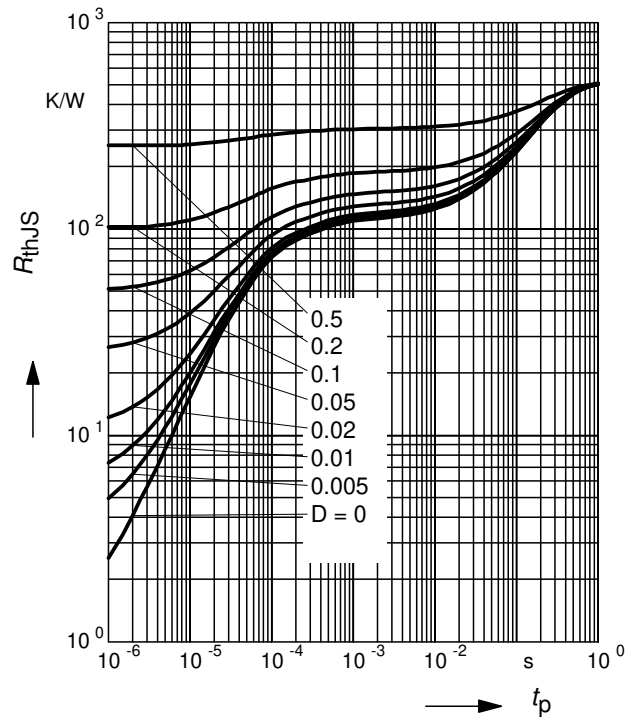
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAS70-04W, BAS70-06W



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

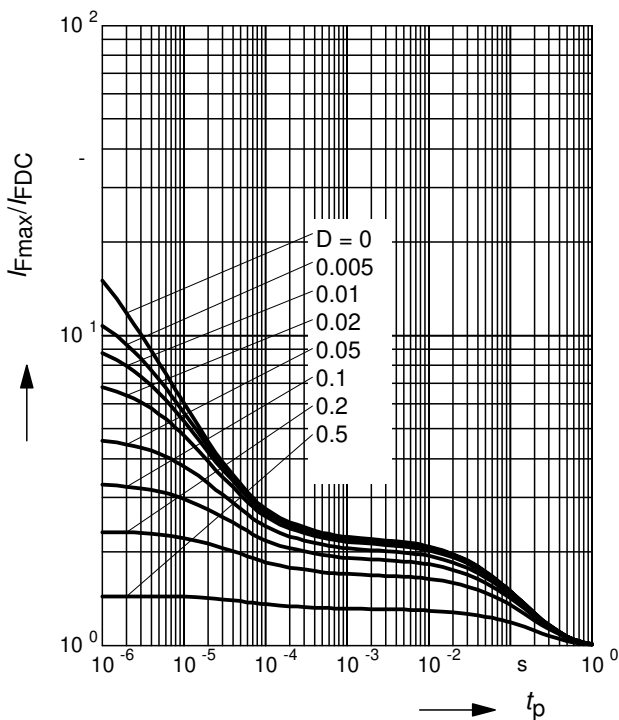
BAS70-05



**Permissible Pulse Load**

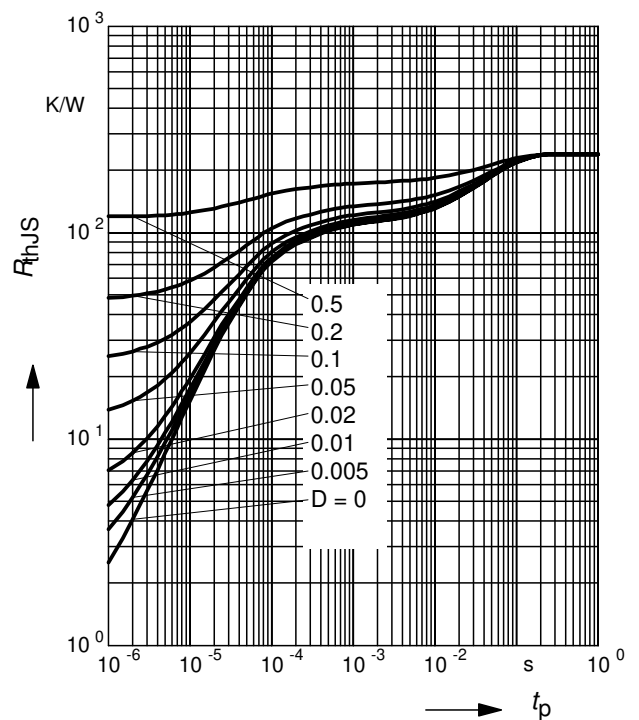
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAS70-05



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

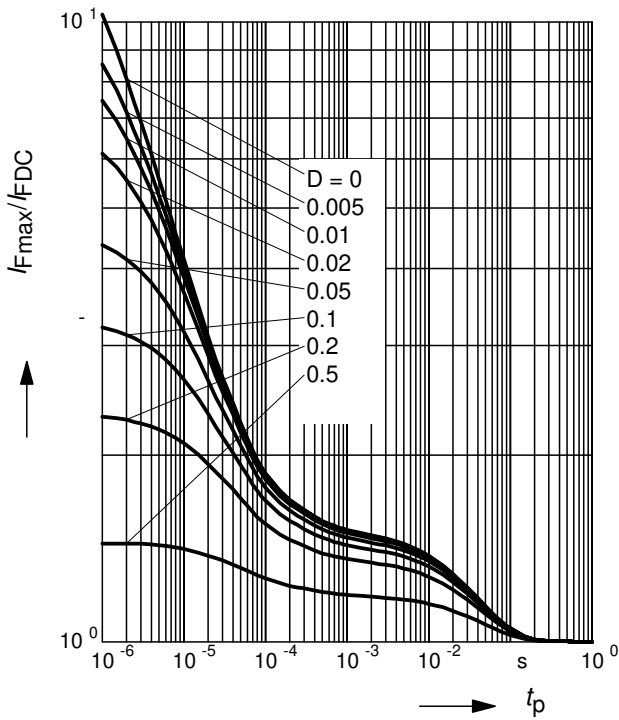
BAS70-05W



**Permissible Pulse Load**

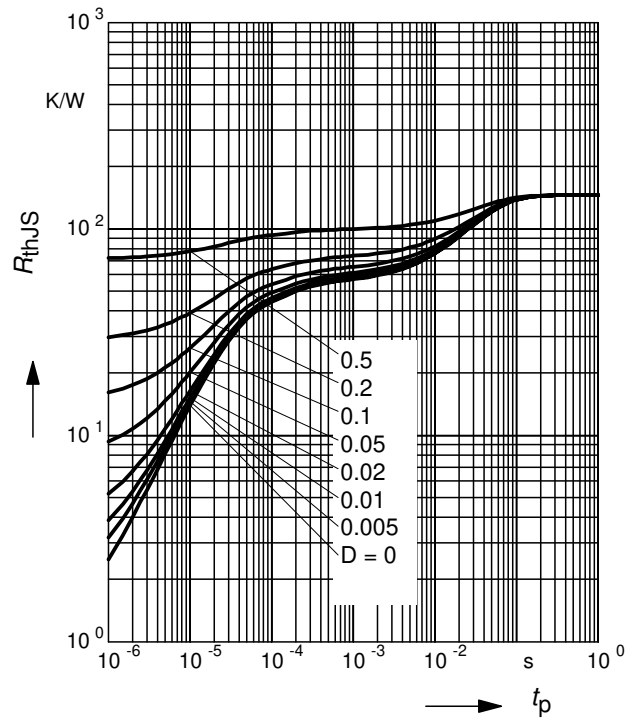
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAS70-05W



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

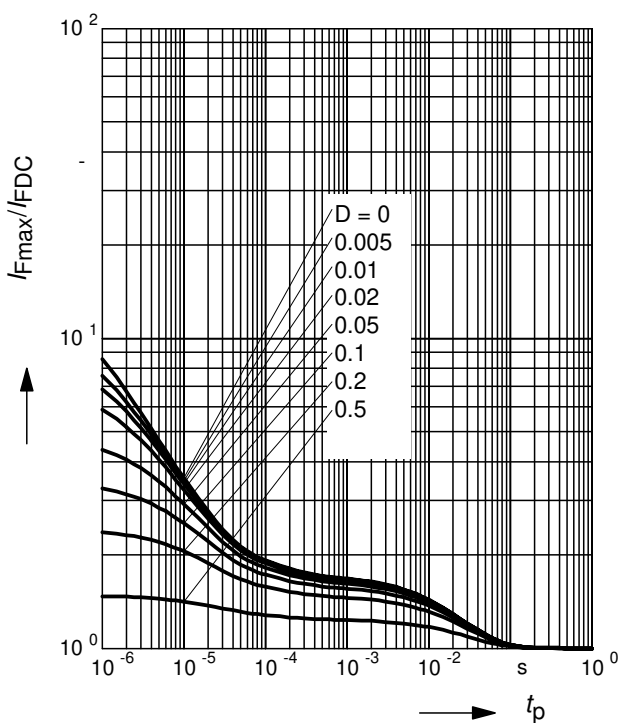
BAS70-07W



**Permissible Pulse Load**

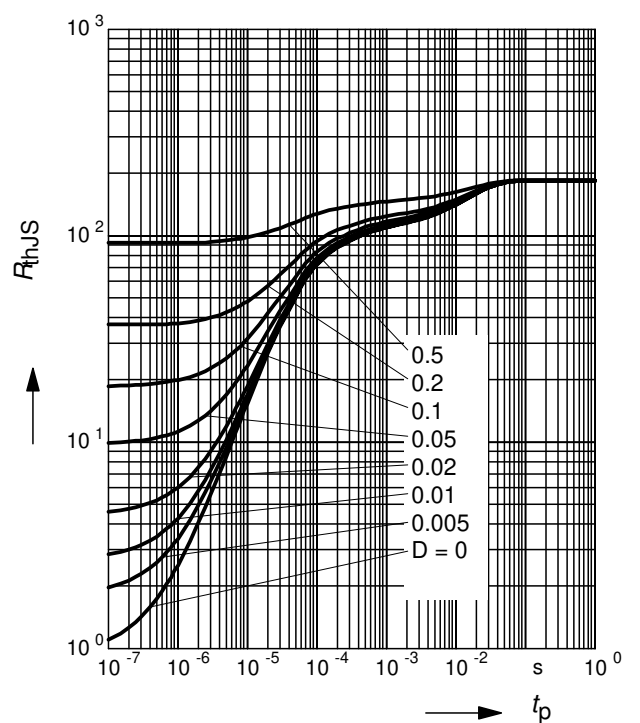
$$I_{Fmax} / I_{FDC} = f(t_p)$$

BAS70-07W



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

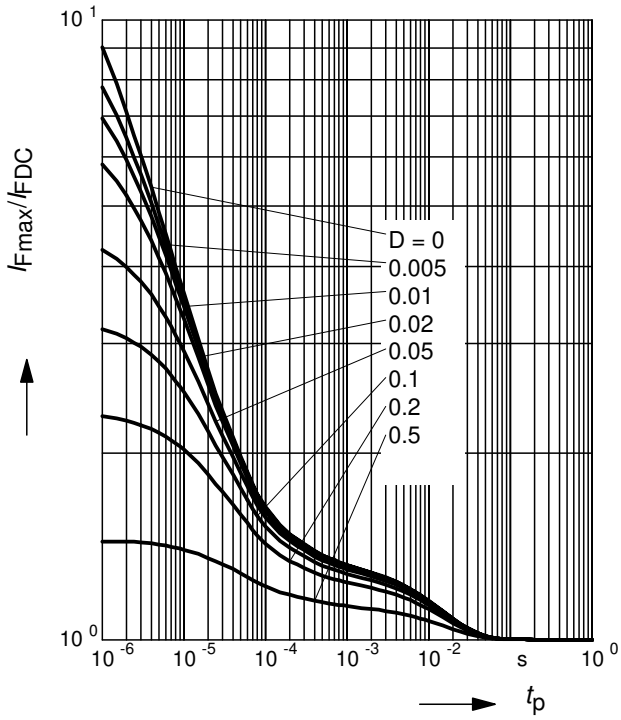
BAS170W



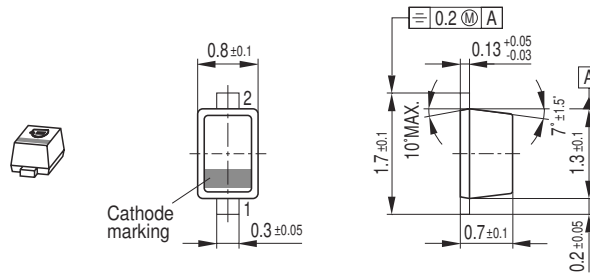
**Permissible Pulse Load**

$$I_{Fmax} / I_{FDC} = f(t_p)$$

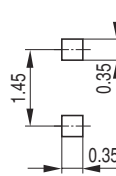
BAS170W



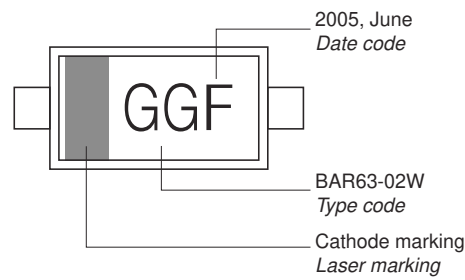
Package Outline



Foot Print

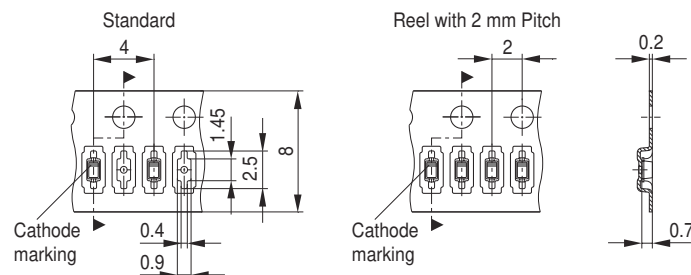


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)  
 Reel ø330 mm = 10.000 Pieces/Reel



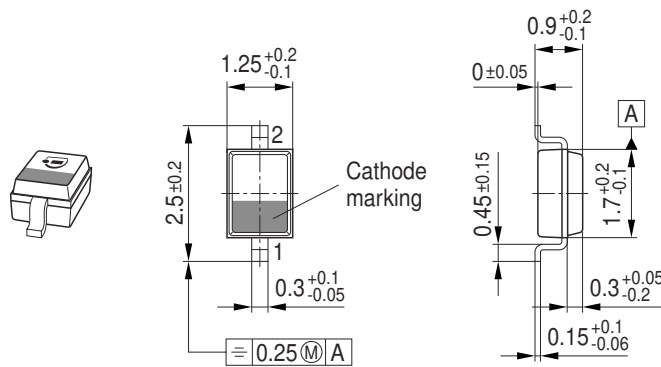
Date Code marking for discrete packages with one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

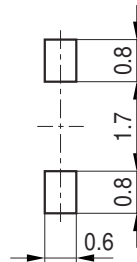
1) New Marking Layout for SC75, implemented at October 2005.



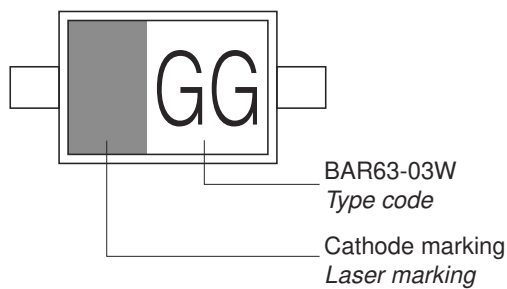
Package Outline



Foot Print

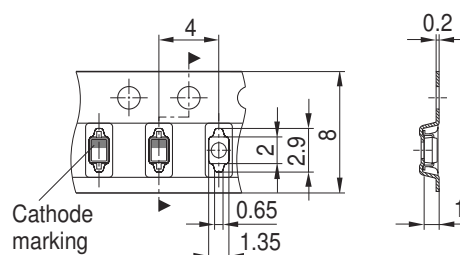


Marking Layout (Example)

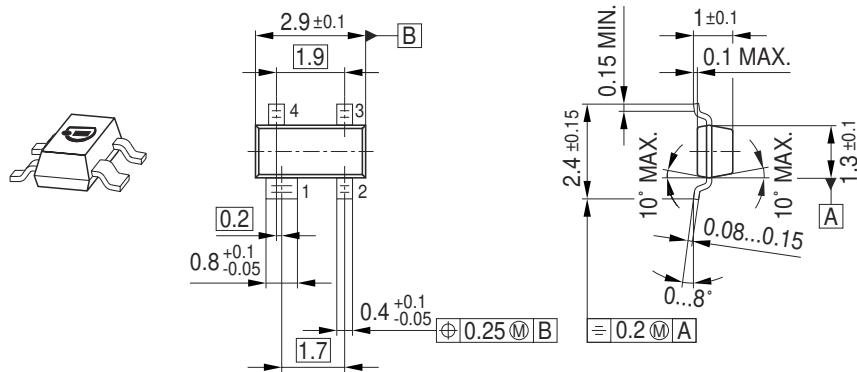


Standard Packing

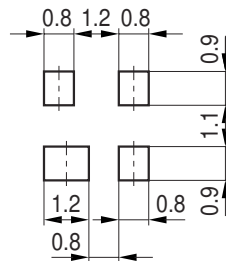
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



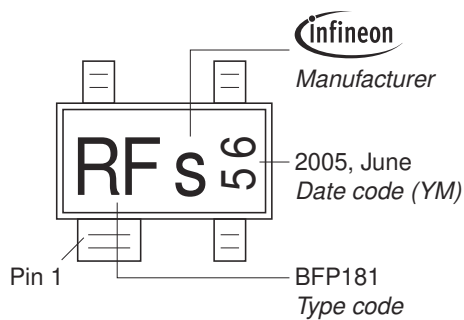
Package Outline



Foot Print

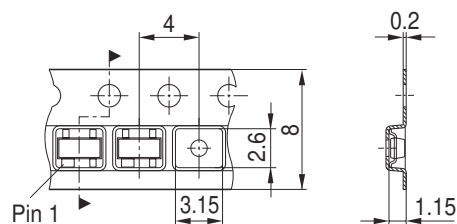


Marking Layout (Example)

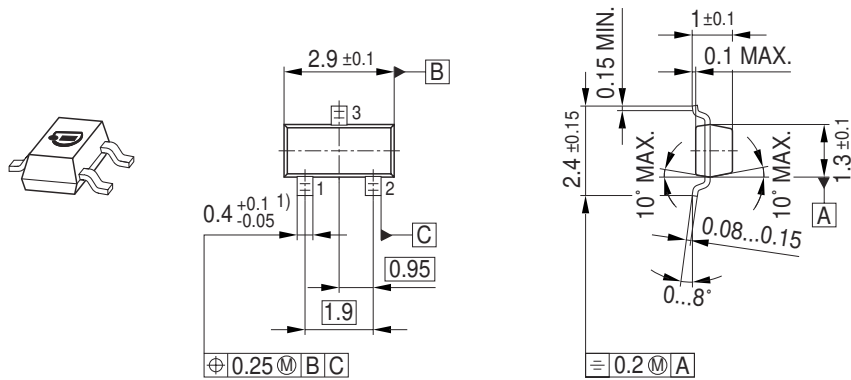


Standard Packing

Reel  $\varnothing 180$  mm = 3.000 Pieces/Reel  
 Reel  $\varnothing 330$  mm = 10.000 Pieces/Reel

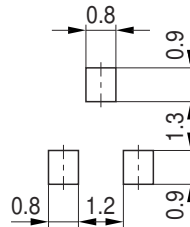


Package Outline

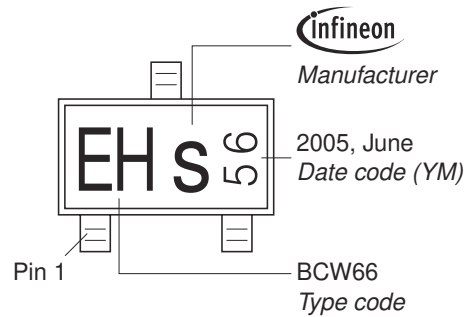


1) Lead width can be 0.6 max. in dambar area

Foot Print

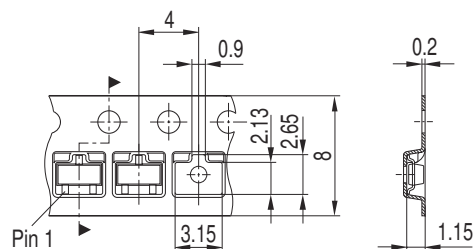


Marking Layout (Example)

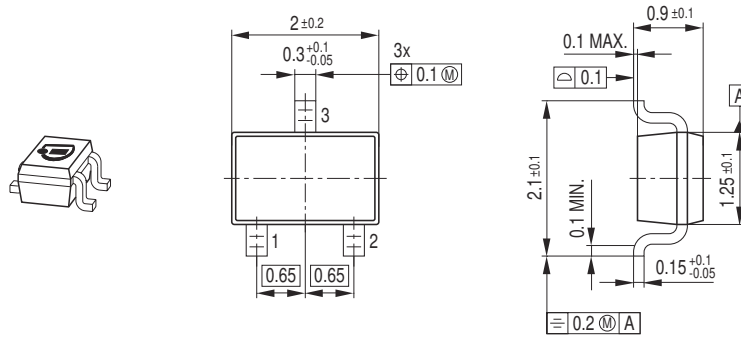


Standard Packing

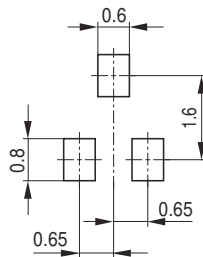
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



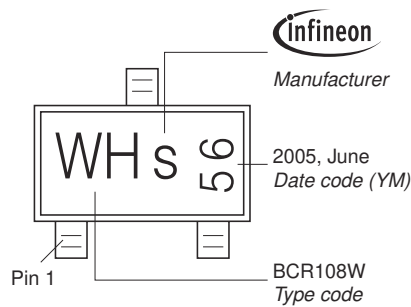
Package Outline



Foot Print

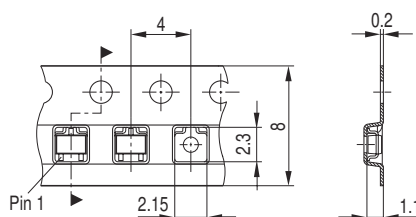


Marking Layout (Example)

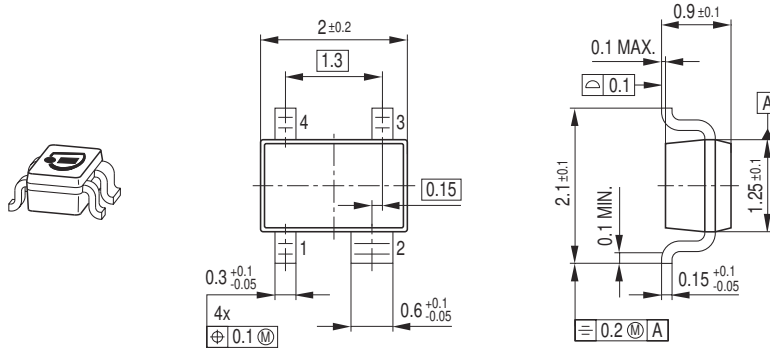


Standard Packing

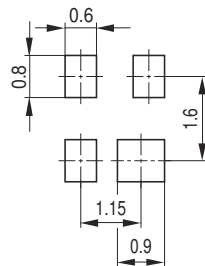
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



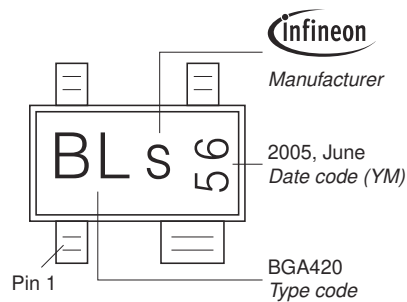
Package Outline



Foot Print

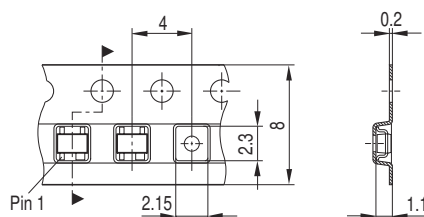


Marking Layout (Example)

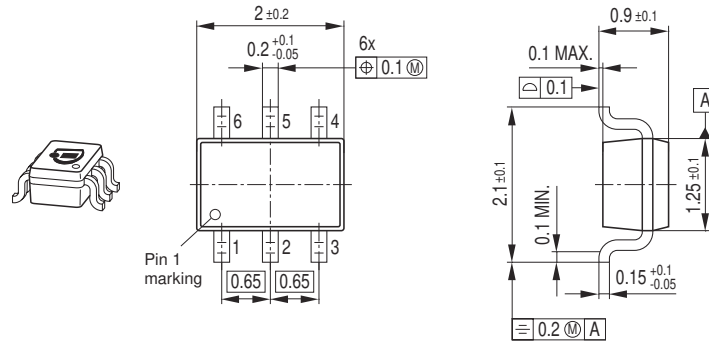


Standard Packing

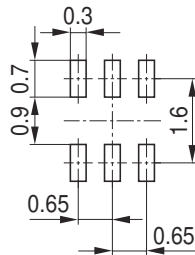
Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel



Package Outline

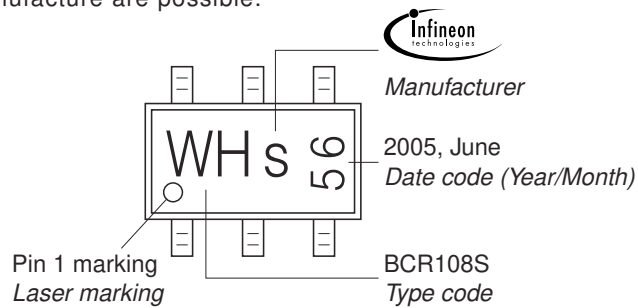


Foot Print



Marking Layout (Example)

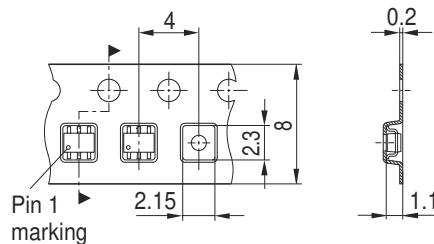
Small variations in positioning of Date code, Type code and Manufacture are possible.



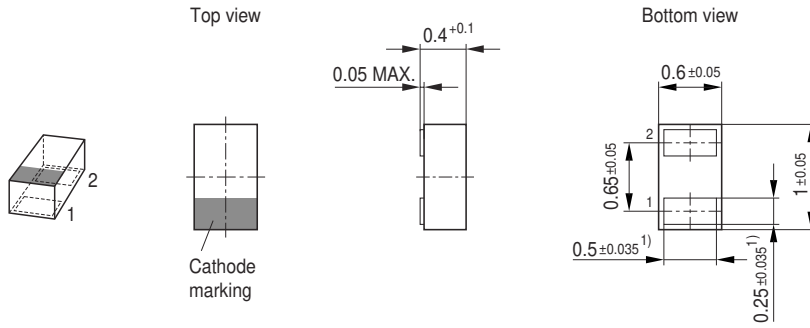
Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



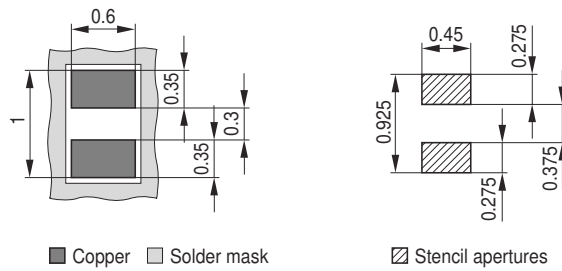
### Package Outline



1) Dimension applies to plated terminal

### Foot Print

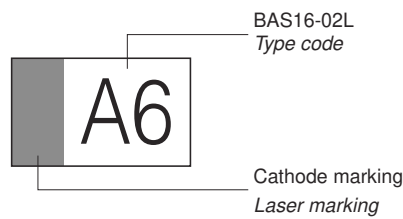
For board assembly information please refer to Infineon website "Packages"



■ Copper □ Solder mask

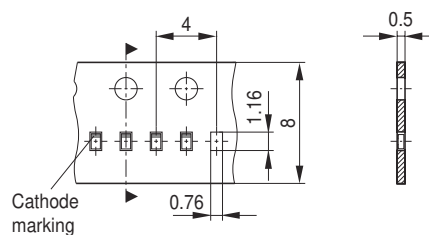
▨ Stencil apertures

### Marking Layout (Example)



### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel  
 Reel ø330 mm = 50.000 Pieces/Reel (optional)



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